

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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UP04211G

Silicon NPN epitaxial planar type

For switching/digital circuits

■ Features

- Two elements incorporated into one package (Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number

• UNR2210 × 2

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	50	V
Collector-emitter voltage (Base open)	V _{CEO}	50	V
Collector current	I_{C}	100	mA
Total power dissipation	P _T	125	mW
Junction temperature	T_{j}	125	°C
Storage temperature	T _{stg}	-55 to +125	°C

■ Package

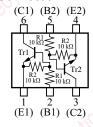
• Code SSMini6-F2

• Pin Name

1: Emitter (Tr1) 4: Emitter (Tr2)
2: Base (Tr1) 5: Base (Tr2)
3: Collector (Tr2) 6: Collector (Tr1)

■ Marking Symbol: 9V

■ Internal Connection

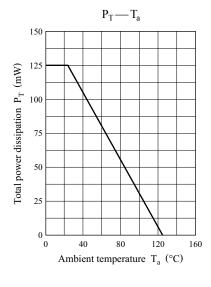


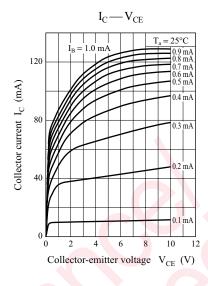
■ Electrical Characteristics $T_a = 25$ °C±3°C

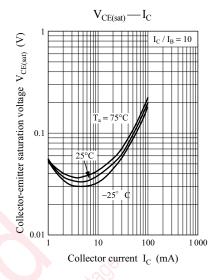
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V_{CBO}	$I_{\rm C} = 10 \mu A, I_{\rm E} = 0$	50	5	8,	V
Collector-emitter voltage (Base open)	V_{CEO}	$I_C = 2 \text{ mA}, I_B = 0$	50	10.0		V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = 50 \text{ V}, I_{E} = 0$	30, 30	2//	0.1	μΑ
Collector-emitter cutoff current (Base open)	I_{CEO}	$V_{CE} = 50 \text{ V}, I_{B} = 0$	Silio		0.5	μΑ
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = 6 \text{ V}, I_{C} = 0$			0.5	mA
Forward current transfer ratio	h_{FE}	$V_{CE} = 10 \text{ V}, I_{C} = 5 \text{ mA}$	35			_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 10 \text{ mA}, I_B = 0.3 \text{ mA}$			0.25	V
Output voltage high-level	V_{OH}	$V_{CC} = 5 \text{ V}, V_{B} = 0.5 \text{ V}, R_{L} = 1 \text{ k}\Omega$	4.9			V
Output voltage low-level	V _{OL}	$V_{CC} = 5 \text{ V}, V_{B} = 2.5 \text{ V}, R_{L} = 1 \text{ k}\Omega$			0.2	V
Input resistance	R_1	0/6,00 NIP.	-30%	10	+30%	kΩ
Resistance ratio	R_1/R_2		0.8	1.0	1.2	_
Transition frequency	f_T	$V_{CB} = 10 \text{ V}, I_{E} = -2 \text{ mA}, f = 200 \text{ MHz}$		150		MHz

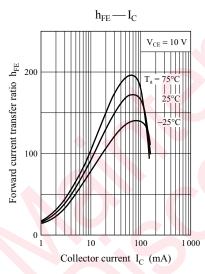
Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

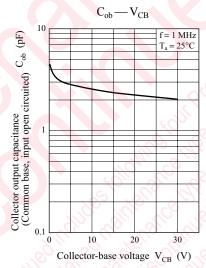
UP04211G Panasonic

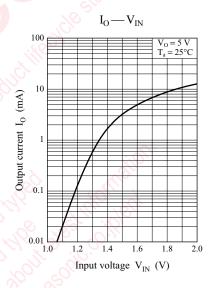


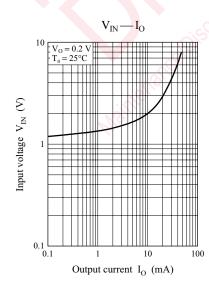










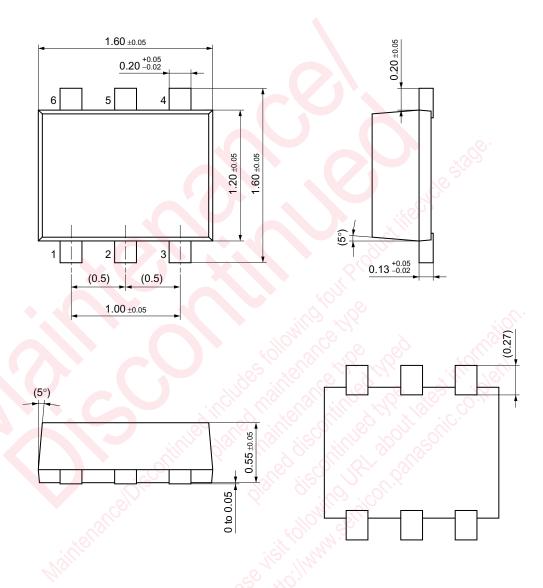


2 SJJ00407AED

Panasonic UP04211G

Unit: mm

SSMini6-F2



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